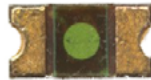


# 0603ESDA-MLP

## ESD suppressor



### Product features

- AEC-Q200 qualified
- Ultra-low capacitance (0.05 pF) ideal for high speed data applications
- Provides Electro Static Discharge (ESD) protection with fast response time (<1 ns) allowing equipment to pass IEC 61000-4-2 Level 4 test
- Single-line, bi-directional device
- 0603 (1608 metric) compact design utilizes less board space

### Applications

- ESD port protection for mobile/smart phones
- Game console ESD port protection
- High speed ESD data port protection
- Set-top-boxes
- Tablets, notebooks, netbooks, laptops
- High definition television (HDTV)
- Media players
- Digital cameras
- Medical equipment
- Computers and peripherals ESD port protection
- Consumer electronics

### Ordering

- Specify part number and packaging suffix (e.g. 0603ESDA-MLP7) 0603ESDA-MLP = part number, 7 = packaging suffix)

### Packaging suffixes

- 7 (Tape and reel, 5 000 parts per 7" diameter reel)

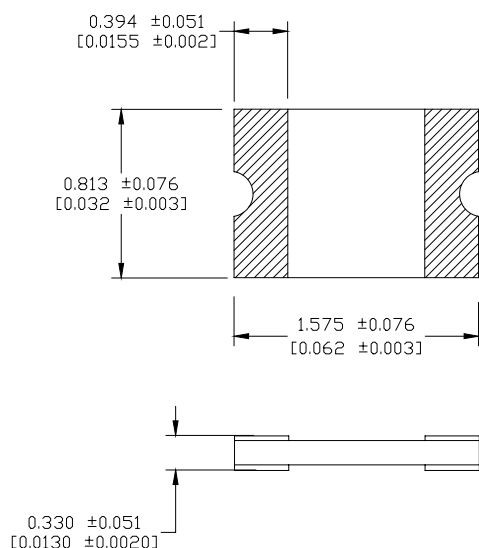
### Product specifications

Part number <sup>4</sup>	Rated voltage (V <sub>dc</sub> ) maximum	Clamping voltage <sup>1</sup> (V) typical	Trigger voltage <sup>2</sup> (V) typical	Capacitance @ 1 MHz (pF) typical	Capacitance @ 1 MHz (pF) maximum	Attenuation change (0–6 GHz) (dB) typical	Leakage current @ 12 V <sub>dc</sub> (nA) typical	ESD capability IEC61000-4-2 Direct discharge (kV) typical	ESD capability IEC61000-4-2 Air discharge (kV) typical	ESD pulse withstand <sup>3</sup> typical
0603ESDA-MLP	30	35	300	0.05	0.15	-0.2	<0.1	8	15	>1000

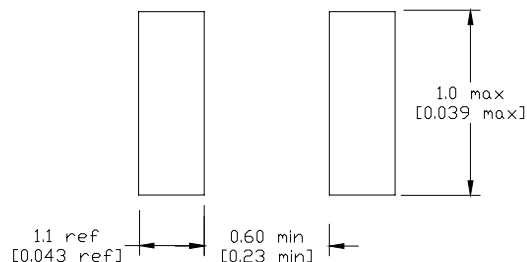
1. Clamping voltage: Per IEC61000-4-2, Level 4 waveform (8 kV direct 30 A) measured 30 ns after initial pulse.
2. Trigger voltage: Trigger measurement made using Transmission Line Pulse (TLP) method.

3. Minor shifting in characteristics may be observed over multiple ESD pulses at very rapid rate.
4. Part number definition: 0603ESDA-MLP  
0603ESDA= Product code and size  
-MLP= Form designation

### Dimensions—mm [in]



### Recommended Pad Layout



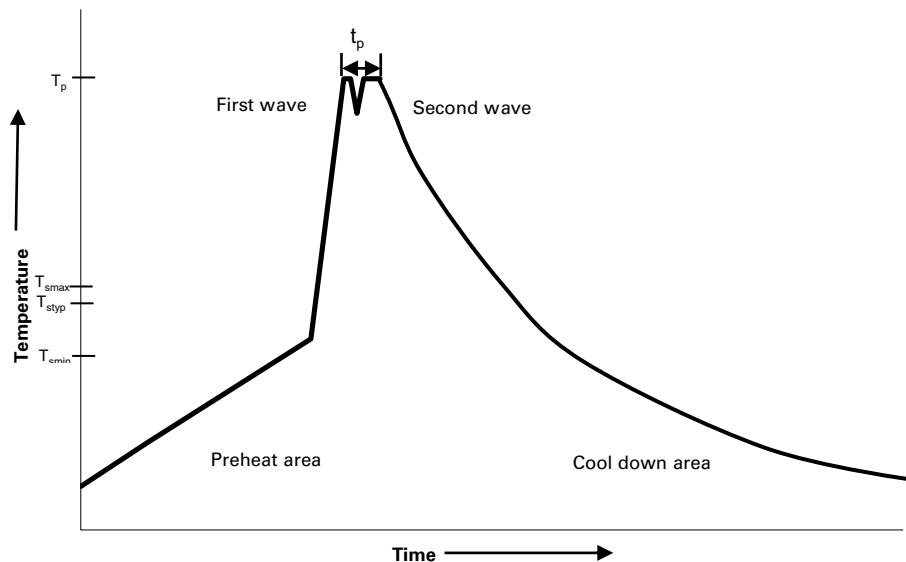
### Design considerations

The location in the circuit for the 0603ESDA-MLP has to be carefully determined. For better performance, the device should be placed as close to the signal input as possible and ahead of any other component. Due to the high current associated with an ESD event, it is recommended to use a “0-stub” pad design (pad directly on the signal/data line and second pad directly on common ground).

### General specifications

Operating temperature: - 55 °C to +125 °C
Storage temperature (component): - 55 °C to +125 °C
Load humidity: 12 VDC per EIA/IS- 722 +85 °C, 85% relative humidity for 1 000 hours
Thermal shock: 10 cycles, - 55 °C to +125 °C, 30 minute dwell time
Moisture resistance: MIL-STD-202G, method 106G, 10 cycles
Mechanical shock: EIA/IS- 722 paragraph 4.9
Mechanical vibration: EIA/IS- 722 paragraph 4.10
Resistance to solvent: EIA/IS- 722 paragraph 4.11

### Wave solder profile



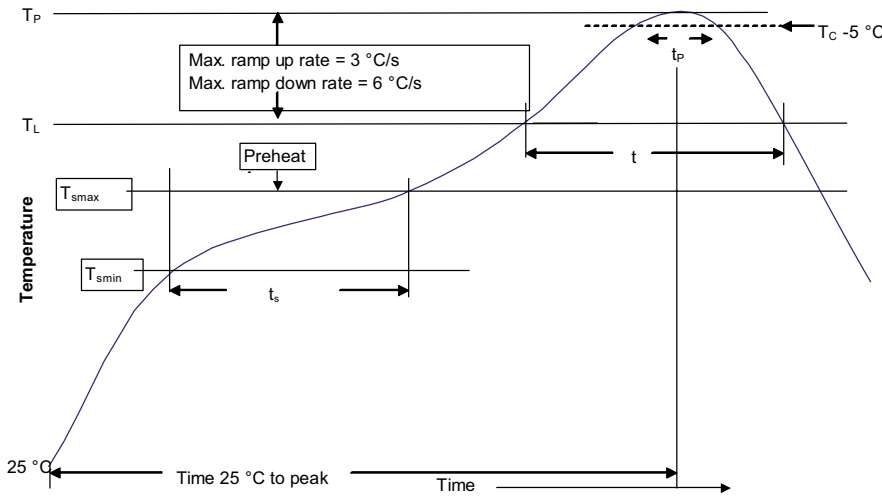
### Reference EN 61760-1:2006

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat		
• Temperature min. ( $T_{smin}$ )	100 °C	100 °C
• Temperature typ. ( $T_{styp}$ )	120 °C	120 °C
• Temperature max. ( $T_{smax}$ )	130 °C	130 °C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	70 seconds	70 seconds
$\Delta$ preheat to max Temperature	150 °C max.	150 °C max.
Peak temperature ( $T_p$ )*	235 °C – 260 °C	250 °C – 260 °C
Time at peak temperature ( $t_p$ )	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down rate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to 25 °C	4 minutes	4 minutes

### Manual solder

+350 °C (4-5 seconds by soldering iron), generally manual/hand soldering is not recommended.

**Solder reflow profile**



**Table 1 - Standard SnPb solder ( $T_c$ )**

Package thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

**Table 2 - Lead (Pb) free solder ( $T_c$ )**

Package thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

**Reference J-STD-020**

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak	<ul style="list-style-type: none"> <li>Temperature min. (<math>T_{smin}</math>)</li> <li>Temperature max. (<math>T_{smax}</math>)</li> <li>Time (<math>T_{smin}</math> to <math>T_{smax}</math>) (<math>t_s</math>)</li> </ul>	<ul style="list-style-type: none"> <li>100 °C</li> <li>150 °C</li> <li>60-120 seconds</li> </ul>
Ramp up rate $T_L$ to $T_p$	3 °C/ second max.	3 °C/ second max.
Liquidous temperature ( $T_L$ ) Time ( $t_L$ ) maintained above $T_L$	<ul style="list-style-type: none"> <li>183 °C</li> <li>60-150 seconds</li> </ul>	<ul style="list-style-type: none"> <li>217 °C</li> <li>60-150 seconds</li> </ul>
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )	20 seconds*	30 seconds*
Ramp-down rate ( $T_p$ to $T_L$ )	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

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**Eaton**  
**Electronics Division**  
1000 Eaton Boulevard  
Cleveland, OH 44122  
United States  
Eaton.com/electronics

Ihr Vertriebspartner:  
**HY-LINE**  
hy-line.de  
LEADER IN TECHNOLOGY.

HY-LINE Power Components  
Vertriebs GmbH  
Inselkammerstr. 10  
D-82008 Unterhaching  
☎ +49 89/ 614 503 -10  
power@hy-line.de

HY-LINE AG  
Hochstrasse 355  
CH-8200 Schaffhausen  
☎ +41 52 647 42 00  
info@hy-line.ch